

DESCRIPTION

Available in SOT-363 package.

FEATURES

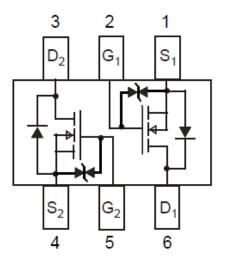
● ESD Protected: 1000V

• Available in SOT-363 package

ORDERING INFORMATION

Package Type	Part Number		
SOT-363	CG	AM2N7002DWC6R	
(SC70-6)	C6	AM2N7002DWC6VR	
Note	V: Halogen free Package R: Tape & Reel		
SPQ: 3,0		00pcs/Reel	
AiT provides all RoHS products			
Suffix " V " means Halogen free Package			

N CHANNEL MOSFET



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PIN DESCRIPTION

1

2

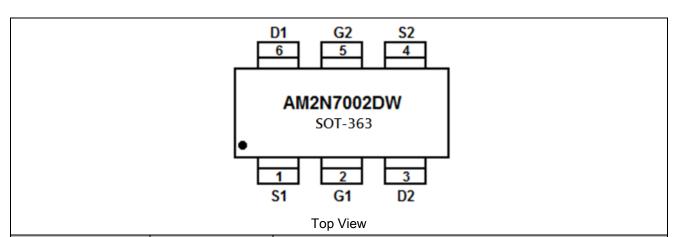
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5

6

D1



Pin# Symbol **Function** S1 Source1 G1 Gate1 D2 Drain2 S2 Source2 G2 Gate2

Drain1

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ABSOLUTE MAXIMUM RATINGS

V _{DSS} , Drain-Source Voltage	60Vdc
V_{DGR} , Drain-Gate Voltage (R _{GS} = 1.0M Ω)	60Vdc
Drain Current	
I _D , Continuous T _C = 25°C NOTE1	±115mAdc
T _C = 100°C NOTE1	±75mAdc
I _{DM} , Pulsed NOTE2	±800mAdc
Gate-Source Voltage	
V _{GS} , Continuous	±20Vdc
V _{GSM} , Non-repetitive (tp ≤ 50μs)	±40Vpk

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

THERMAL CHARACTERISTICS

Parameter	Symbol	Max.	Unit
Total Device Dissipation	P _D	380	mW
Per Device		250	
FR-5 Board NOTE1			
T _A = 25°C			
Derate above 25°C		3.0	mW/°C
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	328	°C/W
Junction and Storage Temperature Range	T _J , T _{STG}	-55 to + 150	°C

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ELECTRICAL CHARACTERISTICS

 $T_A = 25$ °C, unless otherwise specified

OFF CHARACTERISTICS Drain-Source Breakdown Voltage Drain Current are Gate Voltage Drain Current are Gate Voltage Drain Current are Gate Poly Leakage Current, Forward VGS = 0, VGS = 0, VGS = 0, VGS = 0	Parameter	Symbol	Conditions		Min.	Тур.	Max.	Unit	
	OFF CHARACTERISTICS								
Zero Gate Voltage Drain Current Ioss Vos = 60Vdc $T_J = 125^{\circ}C$ - - 500 μAdc Gate-Body Leakage Current, Forward Iosss Vos = 20Vdc - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - - -	Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0$, $I_D = 10 \mu Adc$		60	-	-	Vdc	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0,	T _J = 25°C	-	-	1.0	μAdc	
Forward Igsss VGS = 20Vdc - - 1 μAdc			V _{DS} = 60Vdc	T _J = 125°C	-	-	500		
Forward IGSSR VGS = -20Vdc - - - -1 μAdc Gate-Body Leakage Current, Reverse IGSSR VGS = -20Vdc - - - -1 μAdc ON CHARACTERISTICS NOTE2 Gate Threshold Voltage VGS(TH) VDS = VGS, ID = 250µAdc 1.0 - 2.0 Vdc On-State Drain Current ID(ON) VDS ≥ 2.0VDS(ON), VGS=10Vdc 500 - - mA Static Drain—Source VDS(ON) VGS = 10Vdc, ID = 500mAdc - - 0.375 Vdc Static Drain—Source TDS(ON) VGS = 10V, ID = 500mAdc - - 0.375 Vdc Static Drain—Source TDS(ON) VGS = 10V, ID = 500mAdc - - 0.375 Vdc Static Drain—Source TDS(ON) VGS = 5.0Vdc, ID = 500mAdc - - 7.5 Onms Static Drain—Source GFS VGS = 5.0Vdc, ID = 200mAdc - - - 7.5 Onms Poward Transconductance GFS	Gate-Body Leakage Current,	lassa					1	μAdc	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Forward	IGSSF	VGS - 20Vuc	V _{GS} = 20Vdc		-	'		
Reverse V _{SS(TH)} V _{DS} = V _{GS} , I _D = 250µAdc 1.0 - 2.0 Vdc On-State Drain Current I _{D(ON)} V _{DS} ≥ 2.0V _{DS(ON)} , V _{GS} =10Vdc 500 - - mA Static Drain-Source V _{DS} (ON) V _{GS} = 10Vdc, I _D = 500mAdc - - 3.75 Vdc On-State Voltage V _{OS} (ON) V _{GS} = 5.0Vdc, I _D = 50mAdc - - 0.375 Vdc Static Drain-Source V _{OS} = 10V, I _D = 50mAdc - - 7.5 - 7.5 - - 7.5 - - 7.5 - - 7.5 - - 7.5 - - 7.5 - - 7.5 - - 7.5 - - 7.5 - - 7.5 - - 7.5 - - 7.5 - - 7.5 - - 7.5 - - 7.5 - - 7.5 - - 7.5 - - 7.5 - </td <td>Gate-Body Leakage Current,</td> <td>looop</td> <td colspan="2" rowspan="2">V_{GS} = -20Vdc</td> <td></td> <td></td> <td>1</td> <td>μΛdc</td>	Gate-Body Leakage Current,	looop	V _{GS} = -20Vdc				1	μΛdc	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Reverse	IGSSR			-	_	-1	μΑαс	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	ON CHARACTERISTICS NOTE2	T							
$ \begin{tabular}{l lllllllllllllllllllllllllllllllllll$	Gate Threshold Voltage	V _{GS(TH)}	$V_{DS} = V_{GS}$, $I_D = 2$	250µAdc	1.0	-	2.0	Vdc	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	On-State Drain Current	I _{D(ON)}	$V_{DS} \ge 2.0 V_{DS(ON)}, V_{GS}=10 Vdc$		500	-	-	mA	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Static Drain-Source	V _{GS} = 10Vdc, I _D = 500mAdc		-	-	3.75	\/d=		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	On-State Voltage	V DS(ON)	$V_{GS} = 5.0 Vdc, I_D = 50 mAdc$		-	ı	0.375	Vdc	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$			V _{GS} = 10V,	T _J = 25°C	ı	1	7.5		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Static Drain-Source	_	I _D = 500mAdc	T _J = 125°C	-	-	13.5	Obassa	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	On-State Resistance	rds(on)	$V_{GS} = 5.0 Vdc,$	T _J = 25°C	-	-	7.5	Onms	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$				T _J = 125°C	-	-	13.5		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Forward Transconductance	g FS	V _{DS} ≥2.0V _{DS(ON)} ,I _D =200mAdc		80	-	_	mS	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	DYNAMIC CHARACTERISTICS								
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Input Capacitance	Cıss	V _{DS} = 25Vcd,		-	-	50		
	Output Capacitance	Coss	$V_{GS} = 0$,		-	-	25	рF	
	Reverse Transfer Capacitance	C _{RSS}	f = 1.0MHz		-	-	5.0		
	SWITCHING CHARACTERISTICS NOTE2								
	Turn-On Delay Time	t _{d(ON)}	$R_G = 25\Omega$, $R_L = 50\Omega$,		-	-	20	nc	
	Turn-Off Delay Time	t _{d(OFF)}			-	-	40	ns	
Source Current Continuous Is Body Diode115 mAdc	BODY-DRAIN DIODE RATINGS								
	Diode Forward On-Voltage	V _{SD}	I _S = 115mAdc, V _{GS} = 0V		-	-	-1.5	Vdc	
Source Current Pulsed I _{SM} 800 mAdc	Source Current Continuous	Is	Body Diode		-	-	-115	mAdc	
	Source Current Pulsed	I _{SM}			-	-	-800	mAdc	

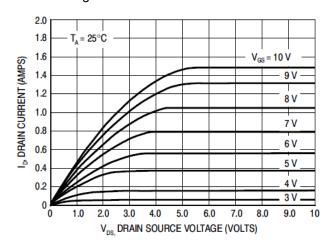
NOTE1: FR-5 = $1.0 \times 0.75 \times 0.062$ in

NOTE2: Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

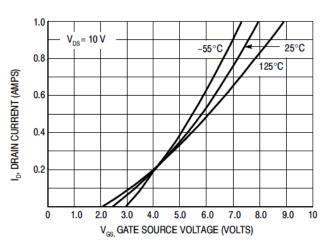
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TYPICAL PERFORMANCE CHARACTERISTICS

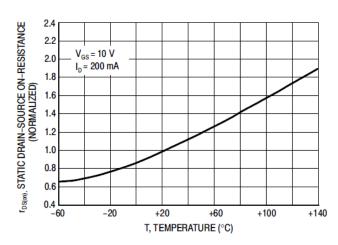
1. Ohmic Region



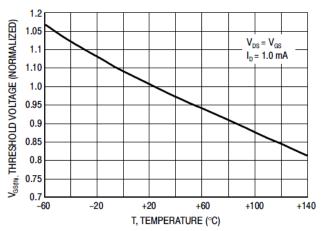
2. Transfer Characteristics



3. Temperature vs. Static Drain-Source On-Resistance



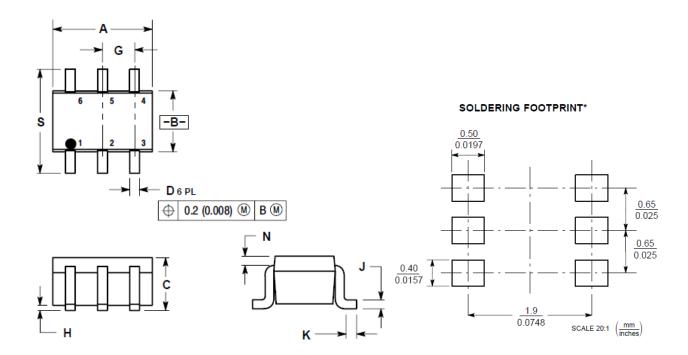
4. Temperature vs. Gate Threshold Voltage



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PACKAGE INFORMATION

Dimension in SOT-363 (SC70-6) Package (Unit: mm)



SYMBOL	MIN	MAX	
Α	1.800	2.200	
В	1.150	1.350	
С	0.800	1.100	
D	0.100	0.300	
G	0.650 BSC		
Н	-	0.100	
J	0.100	0.250	
K	0.100	0.300	
N	0.200 REF		
S	2.000	2.200	

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